

ON Semiconductor				10/16/2019	
Base Part				HF	Pb-free
Orderable Part		FAN7930MX	Total weight (mg)		80.792
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	2.16	Silicon (Si)	7440-21-3	100	
Die Attach	1.144	Silver (Ag)	7440-22-4	74	
		Phenolic Resin-2	54208-63-8	26	
Lead Frame	31.136	Zinc (Zn)	7440-66-6	0.12525694	
		Iron (Fe)	7439-89-6	2.35097636	
		Copper (Cu)	7440-50-8	97.44026208	
		Phosphorus (P)	7723-14-0	0.08350462	
Mold Compound-Black	45.29	Ortho Cresol Novolac Resin	29690-82-2	6.24862	
		Carbon Black (C)	1333-86-4	0.19871936	
		Silica (SiO2)	14464-46-1	87.03908147	
		Phenolic Resin (Novolac)	9003-35-4	6.51357916	
Plating	0.435	Silver (Ag)	7440-22-4	1.6091954	
		Palladium (Pd)	7440-05-3	3.44827586	
		Nickel (Ni)	7440-02-0	92.87356322	
		Gold (Au)	7440-57-5	2.06896552	
Wire Bond - Au	0.627	Gold (Au)	7440-57-5	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					